IN THE UNITED STATES PATENT AND TRADEMARK OFFICE	ATTORNEY DOCKET NO.:	SERIAL NO.:
INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR §1.56, §1.97, and §1.98 **PTO-1449 FORM** Sheet 1 of 4	38203-6080C	10/727,081
	APPLICANTS: Smith et al.	
	FILING DATE: 12/02/2003	GROUP ART UNIT: Unknown 2851

U.S. PATENT DOCUMENTS

† EX'R INITIAL	*REF. #	PATENT NUMBER	DATE	NAME	U.S. CLASS/ SUBCLASS	FILING DATE (If appropriate)
VH	A*	4,861,148	08/29/89	Santo *et al.*	350/505	03/11/87
	B*	5,285,236	02/08/94	Jain	355/53	09/30/92
	C*	5,402,224	3/28/95	Hirukawa et al.	356/124	9/24/93
	D*	5,438,413	08/01/95	Mazor *et al.*	356/363	03/03/93
	E*	5,615,006	3/25/97	Hirukawa et al.	356/124	6/6/95
	F*	5,757,507	05/26/98	Ausschnitt *et al.*	356/401	11/20/95
	G*	5,877,861	3/2/99	Ausschnitt *et al.*	356/401	11/14/97
	H*	5,894,350	4/13/99	Hsieh et al.	356/399	6/12/98
	I*	6,079,256	06/27/00	Bareket	73/105	12/07/98
	J*	6,143,621	11/07/00	Tzeng *et al.*	438/401	06/14/99
	K*	6,259,525	7/10/01	David	356/399	2/24/00

FOREIGN PATENT DOCUMENTS

† EX'R INITIAL	*REF. #				TRANSLATION (YES/NO)
		NONE			

OTHER DOCUMENTS

† EX'R INITIAL	*REF. #	CITATION (Author, Article Title, Journal/Book Title, Date, Pertinent Pages, etc.)
VH	L*	Armitage Jr., J.D. and Kirk, J.P., "Analysis of overlay distortion patterns", *SPIE*, 921:207-222, (1988)
	M*	Bjorkholm *et al.*, "Reduction imaging at 14 nm using multilayer-coated optics: printing of features smaller than 0.1 μm", *J. Vac. Sci. Technol.B.*, 8(6):1509-1543, (1990)
	N*	Brunner, T.A., "Impact Of Lens Aberrations On Optical Lithography", *IBM Journal of Research and Development: Optical Lithography* 41(1-2):57-67, (1997) (http://www.research.ibm.com/journal/rd/411/brunner.html)

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TITLE: METHOD AND APPARATUS FOR SELF-REFERENCED PROJECTION LENS DISTORTION MAPPING

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INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR §1.56, §1.97, and §1.98 **PTO-1449 FORM** Sheet 2 of 4	38203-6080C	10/727,081
	APPLICANTS: Smith et al.	
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CH	O*	Bruning *et al.*, "Optical Lithography – Thirty years and three orders of magnitude", *SPIE*, 3051:14-27, (1997)
	P*	Cote *et al.*, "Micrascan™ III-performance of a third generation, catadioptric step and scan lithographic tool", *SPIE*, 3051:806-816, (1997)
	Q*	DeJule, R., "Mix-and Match: A Necessary Choice", *Semiconductor International*, 23(2): 66-76, (Feb, 2000)
	R*	Dooly, T. and Yang, Y., "Stepper matching for optimum line performance", *SPIE*, 3051:426-432, (1997)
	S*	Goodwin, F. and Pellegrini, J.C., "Characterizing Overlay Registration of Concentric 5X and 1X Stepper Exposure Fields using Interfield Data", *SPIE*, 3050:407-417, (1997)
	T*	Handbook of Microlithography, Micromachining, and Microfabrication, Book: Vol. 1, "Microlithography", Rai-Choudhury, P. (Ed.), SPIE Optical Engineering Press, SPIE, Bellingham, Washington, pages 417-418, (1997)
	U*	Hasan *et al.*, "Automated Electrical measurements of Registration Errors in Step-and-Repeat optical Lithography Systems", *IEEE Transactions on Electron Devices*, ED27(12):2304-2312, (1980)
	V*	Kemp *et al.*, "A "golden standard" wafer design for optical stepper characterization", *SPIE*, 1464:260-266, (1991)
	W*	KLA 5105, "Linewidth and Misregistration System", KLA 5105 Product Specifications, *KLA Instruments Corporation*, 2 pages, (1995)
	X*	KLA 5200, "Value-added Overlay Metrology for Advanced Lithography", KLA 5200 Product Specifications, *KLA Instruments Corporation*, 2 pages, (1996)
	Y*	Kodama, K. and Matsubara, E., "Measuring system XY-5i", *SPIE*, 2439:144-155, (1995)
	Z*	Leica LMS IPRO, "Fully automated mask and wafer metrology system", *Leica*, pamphlet pages 1-5.
	AA*	Lin, B.J., "The Attenuated Phase-Shifting Mask", *Solid State Technology*, Special Series/Advanced Lithography, 35(1):43-47, (January, 1992)
	AB*	MacMillen, D. and Ryden, W.D., "Analysis of image field placement deviations of a 5X microlithographic reduction lens", *SPIE*, 334:78-89, (1982)
	AC*	Martin *et al.*, "Measuring Fab Overlay Programs", *SPIE*, 3677:64-71(1999)
	AD*	Mc Fadden, E.A. and Ausschnitt, C.P., "A Computer Aided Engineering Workstation For Registration Control", *SPIE*, 1087:255-266, (1989)

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	APPLICANTS: Smith et al.	
	FILING DATE: 12/02/2003	GROUP ART UNIT: Unknown 2857

U9	AE*	Mulkens *et al.*, "ArF Step And Scan Exposure System For 0.15 μm Technology Node?", *SPIE*, 3679:506-521, (1999)
	AF*	Newnam, B.E. and Viswanathan, V.K., "Development of XUV projection lithograph at 60-80 nm", *SPIE*, 1671:419-436, (1992)
	AG*	Numerical Recipes, "The Art of Scientific Computing", Press et al. (Eds.), Cambridge University Press, New York, pages 52-64 (1990).
	AH*	Pellegrini, J.C., "Comparisons of Six Different Intrafield Control Paradigms in an Advanced Mix-and-Match Environment", *SPIE*, 3050:398-406, (1997)
	AI*	Pellegrini *et al.*, "Super Sparse Overlay Sampling Plans: An Evaluation of Methods and Algorithms for Optimizing Overlay Quality Control and Metrology Tool Throughput", *SPIE*, 3677:72-82, (1999)
	AJ*	Preil, M.E. and McCormack, J.F.M., "A New Approach to Correlating Overlay and Yield", *SPIE*, 3677:208-216, (1999)
	AK*	Quaestor Q7, "Fully Automated Optical Metrology System for Advanced IC Production", Quaestor Q7 Product Specification, *BIO -RAD*, 2 pages
	AL*	Raugh, M.R., "Error estimation for lattice methods of stage self-calibration", *SPIE*, 3050:614-625, (1997)
	AM*	Sullivan, N.T., "Semiconductor Pattern Overlay", *SPIE Critical Reviews of Optical Science and Technology*, CR52:160-188, (1994)
	AN*	Takac *et al.*, "Self-calibration in two-dimensions: the experiment", *SPIE*, 2725:130-146, (1996)
	AO*	van den Brink *et al.*, "Direct-referencing automatic two-points reticle-to-wafer alignment using a projection column servo system", *SPIE*, 633:60-71, (1986)
	AP*	van den Brink *et al.*, "Matching Management Of Multiple Wafer Steppers Using A Stable Standard And A Matching Simulator", *SPIE*, 1087:218-232, (1989)
	AQ*	van den Brink *et al.*, "Matching Of Multiple Wafer Steppers For 0.35 μm Lithography Using Advanced Optimization Schemes", *SPIE*, 1926:188-207, (1993)
	AR*	van den Brink *et al.*, "Matching Performance For Multiple Wafer Steppers Using An Advanced Metrology Procedure", *SPIE*, 921:180-197, (1988)
	AS*	van den Brink *et al.*, "New 0.54 Aperture i-Line Wafer Stepper With Field By Field Leveling Combined With Global Alignment", *SPIE*, 1463:709-724, (1991)

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Carl W. Li	2/22/05

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Sheet 4 of 4	APPLICANTS: Smith et al.	
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CSF	AT*	van Schoot *et al.*, "0.7 NA DUV Step & Scan System For 150nm Imaging With Improved Overlay", *SPIE*, 3679:448-463, (1999)
	AU*	Yost, A. and Wu, W., "Lens matching and distortion testing in a multi-stepper, sub-micron environment", *SPIE*, 1087:233-244, (1989)
	AV*	Zavecz *et al.*, "Life Beyond Mix-and-Match: Controlling Sub-0.18 μm Overlay Errors ", *Semiconductor International*, 23(8):205,206,208,210,212 and 214, (July, 2000)
	AW*	Zavecz, T.E., "Machine Models and Registration", *SPIE Critical Reviews of Optical Science and Technology*, CR52:134-159 (1994).

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